East 8 WPIDJPO

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1	r Hits 1625192	Search Text	DB	Time stamp
'	1023192	etch\$ or patern\$ or remov\$	JPO;	2004/10/15 10:36
2	2012874	(bond\$ pad) or (contact pad)	DERWENT	
-	2012074	(bonds pad) or (contact pad)	JPO;	2004/10/15 10:37
3	307877	resist or photoresist or mask or photomask	DERWENT	
1		Prototesist of mask of photomask	JPO;	2004/10/15 10:38
4	17602	passivat\$	DERWENT	
]		1	JPO;	2004/10/15 10:38
5	641458	adhes\$	DERWENT	0004445445
			JPO; DERWENT	2004/10/15 10:38
6	2225243	adhes\$ layer	JPO;	2004/40/45 40:00
	1		DERWENT	2004/10/15 10:38
7	17348	(etch\$ or patern\$ or remov\$) and ((bond\$ pad) or (contact	JPO;	2004/10/15 10:39
		pad)) and (resist or photoresist or mask or photomask) and	DERWENT	2004/10/15 10:39
		(passivat\$ or (adhes\$ layer))	DEITTE	
8	36628	(bond\$ with pad) or (contact with pad)	JPO;	2004/10/15 10:39
	440000	u 🛕	DERWENT	200 11 10/10 10:00
9	149036	adhes\$ with layer	JPO;	2004/10/15 10:40
10	9046	(-4.1.0 · · · · · · · · · · · · · · · · · · ·	DERWENT	1 = 2 % (6) (6) (6)
10	8016	(etch\$ or patern\$ or remov\$) with (adhes\$ with layer)	JPO;	2004/10/15 10:40
11	7928	passivott with laws	DERWENT	
1	1920	passivat\$ with layer	JPO;	2004/10/15 10:40
12	1765	/etch\$ or notorn\$ or remail\$) with /	DERWENT	
	1700	(etch\$ or patern\$ or remov\$) with (passivat\$ with layer)	JPO;	2004/10/15 10:40
13	635	(((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or	DERWENT	
		((etch\$ or patern\$ or remov\$) with (adnes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer)))	JPO;	2004/10/15 10:41
	}	and (resist or photoresist or mask or photomask) and	DERWENT	
	1	((bond\$ pad) or (contact pad))		
14	635	(etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or	JPO;	00044045
		remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or	DERWENT	2004/10/15 10:41
İ .		remov\$) with (passivat\$ with layer))) and (resist or	DEKANEIAI	
1	į į	photoresist or mask or photomask) and ((bond\$ pad) or		
145		(contact pad)))		
15	20586	bond\$ with pad	JPO;	2004/10/15 10:41
   16		46.4.2	DERWENT	2004/10/13 10:41
16	73	((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or	JPO;	2004/10/15 11:15
	1	removs) with (adhes\$ with laver)) or ((etch\$ or patern\$ or	DERWENT	
		remov\$) with (passivat\$ with layer))) and (resist or		
	ŀ	photoresist or mask or photomask) and ((bond\$ pad) or		
17	562	(contact pad)))) and (bond\$ with pad)		ľ
	002	((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or	JPO;	2004/10/15 11:15
		remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or	DERWENT	
		photoresist or mask or photomask) and ((bond\$ pad) or		
	[ ]	(contact pad)))) not (bond\$ with pad)		
18	57	(((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or	I IDO:	000444044= 1
l	1 i	remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or	JPO;	2004/10/15 11:15
	11	remov\$) with (passivat\$ with layer))) and (resist or	DERWENT	
	1 1	photoresist or mask or photomask) and ((bond\$ nad) or		
	(	contact pad)))) not (bond\$ with pad)) and solder\$		
		Title 1. (2 that pad) and solucing		

est & WPID, JPO L Number DB Time stamp 1625192 etch\$ or patern\$ or remov\$ JPO; 2004/10/15 10:36 DERWENT 2 2012874 (bond\$ pad) or (contact pad) JPO: 2004/10/15 10:37 DERWENT 3 307877 resist or photoresist or mask or photomask JPO: 2004/10/15 10:38 **DERWENT** 4 17602 passivat\$ JPO: 2004/10/15 10:38 DERWENT 5 641458 adhes\$ JPO: 2004/10/15 10:38 DERWENT 6 2225243 adhes\$ layer JPO: 2004/10/15 10:38 DERWENT 7 17348 (etch\$ or patern\$ or remov\$) and ((bond\$ pad) or (contact JPO: 2004/10/15 10:39 pad)) and (resist or photoresist or mask or photomask) and **DERWENT** (passivat\$ or (adhes\$ layer)) 8 36628 (bond\$ with pad) or (contact with pad) JPO: 2004/10/15 10:39 DERWENT 9 149036 adhes\$ with layer JPO: 2004/10/15 10:40 DERWENT 10 8016 (etch\$ or patern\$ or remov\$) with (adhes\$ with layer) JPO: 2004/10/15 10:40 DERWENT 11 7928 passivat\$ with layer JPO: 2004/10/15 10:40 DERWENT 12 1765 (etch\$ or patern\$ or remov\$) with (passivat\$ with layer) JPO: 2004/10/15 10:40 DERWENT 13 635 (((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or JPO: 2004/10/15 10:41 ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) DERWENT and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)) 14 635 (etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO: 2004/10/15 10:41 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad))) 15 20586 bond\$ with pad JPO; 2004/10/15 10:41 DERWENT 16 ((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO; 2004/10/15 11:15 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) and (bond\$ with pad) 17 562 ((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO: 2004/10/15 11:15 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad) 18 (((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO; 2004/10/15 11:25 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or **DERWENT** remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$ 19 505 (((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO: 2004/10/15 11:26 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)

<u></u>	_	- <sub>1</sub>			
2	0	33	((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or	JPO; DERWENT	2004/10/15 11:33
			photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$		
		1	or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$		
			with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$		
			with layer))) and (resist or photoresist or mask or photomask)		]
1			and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216")		
2	1	472	((((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or	JPO;	2004/10/15 11:33
			remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or	DERWENT	2004/10/13 11:55
			remov\$) with (passivat\$ with layer))) and (resist or		
			photoresist or mask or photomask) and ((bond\$ pad) or		
			(contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$		
ı			with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$		
			with layer))) and (resist or photoresist or mask or photomask)		
		1	and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad))	1	
			and solder\$)) not (((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or	1	
			((etch\$ or patern\$ or remov\$) with (passivat\$ with layer)))		
			and (resist or photoresist or mask or photomask) and		
			((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not		
			((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or		
			remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or		
			photoresist or mask or photomask) and ((bond\$ pad) or		
			(contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216"))		
22	2	8	(((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or	JPO;	2004/10/15 11:35
			remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or	DERWENT	
	,		remov\$) with (passivat\$ with layer))) and (resist or		
		1	photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((etch\$ or patern\$		
			or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$		
		1	with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$		
			with layer))) and (resist or photoresist or mask or photomask)		
			and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad))		
!		[	and solder\$)) not (((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or		
			((etch\$ or patern\$ or remov\$) with (passivat\$ with layer)))		
			and (resist or photoresist or mask or photomask) and		
			((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not		
	į		((((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or remov\$) with (adhes\$ with lover)) or ((etch\$ or patern\$ or		
			remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or		
			photoresist or mask or photomask) and ((bond\$ pad) or		
	Ì		(contact pad)))) not (bond\$ with pad)) and solder\$)) and		
<u> </u>			("438" or "216"))) and ("156" or "437" or "257")		j

		T		
23	464	(((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or	JPO;	2004/10/15 11:35
		remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or	DERWENT	
		remov\$) with (passivat\$ with layer))) and (resist or		
ł		photoresist or mask or photomask) and ((bond\$ pad) or		
		(contact pad)))) not (bond\$ with pad)) not (((etch\$ or patern\$		
		or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$		
		with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$		
ı		with layer))) and (resist or photoresist or mask or photomask)		
		and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad))		
		and solder\$)) not (((((etch\$ or patern\$ or remov\$) and	ŀ	
		((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or		
1		((etch\$ or patern\$ or remov\$) with (passivat\$ with laver)))		
		and (resist or photoresist or mask or photomask) and		
	1	((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not		
		((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or		
		remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or		
	ĺ	remov\$) with (passivat\$ with layer))) and (resist or	•	
	1	photoresist or mask or photomask) and ((bond\$ pad) or		
		(contact pad)))) not (bond\$ with pad)) and solder\$)) and		
İ		("438" or "216"))) not ((((((etch\$ or patern\$ or remov\$) and		
1		((((etch\$ or patern\$ or remov\$) with (adhes\$ with laver)) or		
1		((etch\$ or patern\$ or remov\$) with (passivat\$ with layer)))		
l		and (resist or photoresist or mask or photomask) and		
ł		((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not		
		((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or		Ĭ
	1	remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or		
1	1 1	remov\$) with (passivat\$ with layer))) and (resist or		
	1 1	photoresist or mask or photomask) and ((bond\$ pad) or		
		(contact pad)))) not (bond\$ with pad)) and solder\$)) not		
		(((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or		
		remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or		
		remov\$) with (passivat\$ with layer))) and (resist or	1	
		photoresist or mask or photomask) and ((bond\$ pad) or	]	
		(contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$		
		or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$	İ	
		with layer)) or ((etch\$ or patern\$ or remov\$) with (adhes\$		
		with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (regist or photograph)		
		with layer))) and (resist or photoresist or mask or photomask)		
		and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad))		
	1	and solder\$)) and ("438" or "216"))) and ("156" or "437" or "257"))		
		401 ]]		1